

Experimental Investigation of pHEMT at 4.2K : Fabrication and Characterization

T. Lucas and Y. Jin
LPN, CNRS, 196, avenue Henri Ravéra, 92222 Bagneux
Cedex, France

Phone : 33 1 4231 7365 Fax : 33 1 4231 7378
e-mail : yong.jin@L2M.CNRS.fr

In this paper, we will present our recent experimental investigation of the pseudomorphic HEMT at 4.2K. Our previous works on the pHEMT at 4.2K have shown that with a large gate surface of $4\mu\text{m}$ by $4000\mu\text{m}$, the equivalent input $1/f$ voltage noise can be less than $1\text{nV}/\sqrt{\text{Hz}}$ when the frequency is higher than 5.5 kHz. However, the large gate surface is translated into a high input capacitance, which induces a low intrinsic cutoff frequency f_c and thus limits device's applicability in various circuits. To decrease this capacitance, HEMTs with a smaller gate surface of $1\mu\text{m}$ by $4000\mu\text{m}$ have then been realized on (Al,In)GaAs/GaAs heterostructures with a InGaAs well of 17nm and a AlGaAs spacer layer of 4nm.

All DC and noise parameters have been characterized at 4.2K. As usual, neither collapse nor kink effect has been detected in the current-voltage characteristics. Drain-current I_{ds} variation from micro to several tens of milli-Amperes can be obtained with a gate-bias variation of about a quarter volt(see Fig.1), and the gate leakage current I_{gs} is limited less than 0.5pA under all bias conditions. The low gate leakage current in this device can then ensure a high input impedance and the shot noise can be less than $0.3\text{fA}/\sqrt{\text{Hz}}$. Under a fixed drain bias V_{ds} of 0.3V, high transconductances g_m ranging from 480mS to 7mS with corresponding I_{ds} of 39mA to 0.1mA have been achieved (see Fig.2). It is interesting to note that by biasing the gate voltage V_{gs} from 0 to -0.4V, the channel resistance (with $V_{ds}=4\text{mV}$) of this device can increase more than 10^9 times from 0.8Ω to $6\text{G}\Omega$. Depending on V_{gs} , the measured input capacitance varies between 13 and 5pF. Taking into account of the above high g_m values, f_c can reach 6GHz.

For the noise measurement, a 4.2K preamplifier is made with the HEMT to be tested. The voltage gain of the device can thus be measured *in-situ* for each noise spectrum acquisition. Then, the value of the voltage gain is used to deduce the equivalent input voltage noise e_n . As an example, with $V_{ds}=0.3\text{V}$ and $I_{ds}=0.5\text{mA}$, the corresponding measured voltage gain is 11.5. The spectrum of e_n (see Fig.3) shows that e_n down to $1.3\text{nV}/\sqrt{\text{Hz}}$ can be reached at 100kHz. As the $1/f$ noise frequency corner in this HEMT can be much higher than 100kHz, its input noise e_n should then be lower than $1\text{nV}/\sqrt{\text{Hz}}$ when the working frequency is higher than 200kHz.

Finally, the investigation of the gate bias shift with the thermal cycle and the I_{ds} - V_{ds} characteristics will be provided; and a systematic study of the $1/f$ noise as the function of V_{ds} and I_{ds} will be reported in detail. So far, this HEMT should be a suitable device for the switch application owing to its extremely large variation of channel resistance. This device should also be used in the low-power preamplifier with a voltage noise level lower than $1\text{nV}/\sqrt{\text{Hz}}$ for operating frequencies higher than 200kHz, and a shot noise level less than $0.3\text{fA}/\sqrt{\text{Hz}}$.

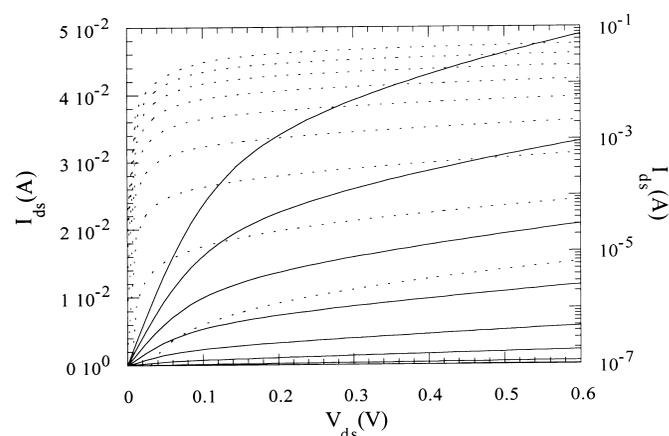


Fig.1 I_{ds} - V_{ds} curves at 4.2K as a function of the gate bias, from top to bottom: $V_{gs}=0\text{V}$ and the steps of -0.03V . I_{ds} are plotted by full lines in decimal scale, and by dashed lines in logarithmic scale for the illustration of I_{ds} under sub-milli Amperes regimes.

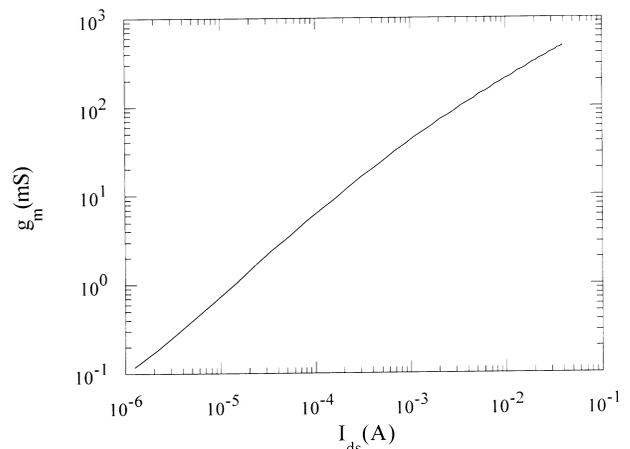


Fig.2 Transconductance g_m as a function of I_{ds} with a fixed drain bias V_{ds} of 0.3V.

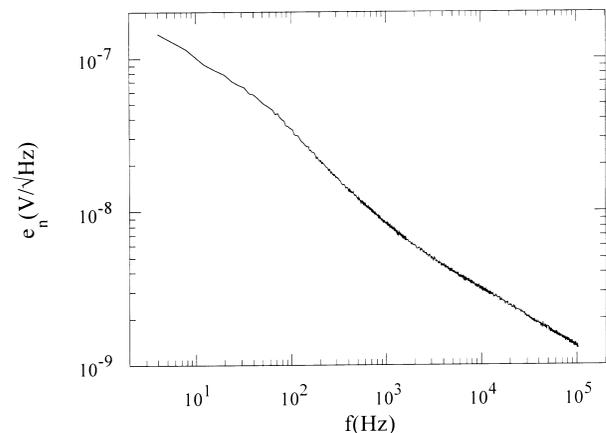


Fig.3 Equivalent input voltage noise e_n spectrum at 4.2K, with $V_{ds}=0.3\text{V}$ and $I_{ds}=0.5\text{mA}$.